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TECHNOLOGY CENTER 2800

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PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2825**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akiro SATO

Group Art Unit: 2825

Application No.: 09/424,500

Examiner: G. Lee

Filed: February 22, 2000

Docket No.: 104788

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING
DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the November 19, 2003 Office Action, the period for reply being extended
by the attached Petition for Extension of Time, please amend the above-identified application
as follows:

IN THE CLAIMS:

Please replace claims 1, 11, 12, 15 and 24 as follows:

1. (Four Times Amended) A method of manufacturing a semiconductor device
comprising:

placing a semiconductor assembly in which a semiconductor chip is secured to
a die pad of a lead frame in a cavity of a mold;

applying a pressure in only one direction to the semiconductor assembly;

least one support pin so as to cause a stress in the lead frame;

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1. (Four Times Amended) A method of manufacturing a semiconductor device comprising:

placing a semiconductor assembly in which a semiconductor chip is secured to a die pad of a lead frame in a cavity of a mold;

applying a pressure in only one direction to the semiconductor assembly by at least one support pin so as to cause a stress in the lead frame;

sealing the semiconductor assembly with a resin injected into the cavity from a resin injection port of the mold, the stress caused in the lead frame preventing the semiconductor assembly from being lifted up or pushed down by the resin when the resin is injected into the cavity; and

pulling the support pin from the cavity into the mold before the resin is cured to release the semiconductor assembly from the pressure applied by the support pin.

2. The method of manufacturing a semiconductor device as defined in claim 1, wherein the support pin is caused to come in contact with the die pad of the semiconductor assembly.

3. The method of manufacturing a semiconductor device as defined in claim 1, wherein a plurality of the support pins are arranged substantially on the axis of the resin injection port.

4. The method of manufacturing a semiconductor device